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TITLE: MAP, LOW PROFILE, 21 X 21 PKG, 624 I/O, 0.8 MM PITCH		DOCUMENT NO: 98ASA00404D	REV: A
		CASE NUMBER: 2240-02	21 FEB 2012
		STANDARD: NON-JEDEC	

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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